

## Soldered SAM on **water** cooled copper heat sink with **25.0** mm diameter **SAM- $\lambda$ -A-25.0w**

SAM chip area            standard:        4mm x 4mm  
Chip thickness           standard:        400  $\mu$ m  
Front side protection   the SAM is protected with a dielectric front layer.

The SAM chip is glued on a gold plated copper heat sink with 25.0 mm  $\varnothing$  using a thermal conducting silver containing epoxy. The glue provides a low thermal resistance between the SAM and the water cooled copper heat sink.

- The **standard** position of the SAM is at the center of the heat sink.
- **Optional** the SAM can be glued on the edge of the heat sink without extra charges.

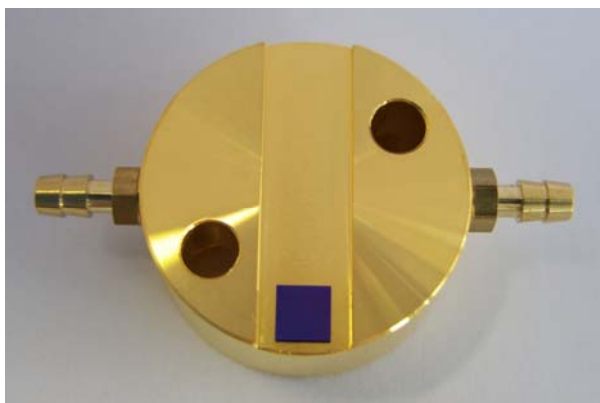
Edge mounted SAM



Centre mounted SAM



Back side



This water cooled heat sink comes with two 1 m long water tubes with an inner diameter of 3 mm.

### Recommended values for cooling water

flow rate:	1000 cm <sup>3</sup> /h = 17 cm <sup>3</sup> /min
pressure difference	0.03 bar
maximum pressure	1 bar

